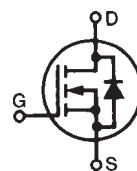


Polar™ Power MOSFET**HiPerFET™**

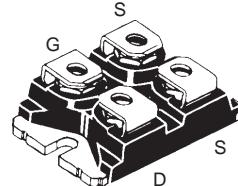
N-Channel Enhancement Mode

Avalanche Rated

Fast Intrinsic Diode

IXFN170N30P

V_{DSS}	= 300V
I_{D25}	= 138A
$R_{DS(on)}$	$\leq 18m\Omega$
t_{rr}	$\leq 200ns$

miniBLOC, SOT-227 B
 E153432

G = Gate **D = Drain**
S = Source

Either Source terminal at miniBLOC can be used as Main or Kelvin Source

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	$T_J = 25^\circ C$ to $150^\circ C$	300	V
V_{DGR}	$T_J = 25^\circ C$ to $150^\circ C$, $R_{GS} = 1M\Omega$	300	V
V_{GSS}	Continuous	± 20	V
V_{GSM}	Transient	± 30	V
I_{D25}	$T_C = 25^\circ C$	138	A
I_{LRMS}	External lead current limit	100	A
I_{DM}	$T_C = 25^\circ C$, pulse width limited by T_{JM}	500	A
I_A	$T_C = 25^\circ C$	85	A
E_{AS}	$T_C = 25^\circ C$	5	J
dV/dt	$I_S \leq I_{DM}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ C$	20	V/ns
P_D	$T_C = 25^\circ C$	890	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	1.6mm (0.062 in.) from case for 10s	300	°C
V_{ISOL}	50/60 Hz, RMS $I_{ISOL} \leq 1mA$	t = 1min t = 1s	2500 V~ 3000 V~
M_d	Mounting torque Terminal connection torque	1.5/13 Nm/lb.in. 1.3/11.5 Nm/lb.in.	
Weight		30	g

Symbol	Test Conditions ($T_J = 25^\circ C$, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{DSS}	$V_{GS} = 0V$, $I_D = 3mA$	300		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 1mA$	2.5	4.5	V
I_{GSS}	$V_{GS} = \pm 20V$, $V_{DS} = 0V$		± 200	nA
I_{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0V$		25 μA 1.5 mA	
$R_{DS(on)}$	$V_{GS} = 10V$, $I_D = 85A$, Note 1		18	$m\Omega$

Features

- Fast intrinsic diode
- Avalanche Rated
- Unclamped Inductive Switching (UIS) rated
- Very low R_{th} results high power dissipation
- Low $R_{DS(ON)}$ and Q_G
- Low package inductance

Advantages

- Low gate charge results in simple drive requirement
- Improved Gate, Avalanche and dynamic dv/dt ruggedness
- High power density

Applications

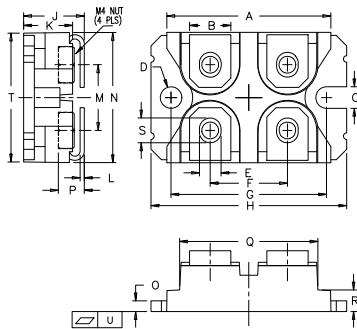
- DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- AC and DC motor control
- Uninterrupted power supplies
- High speed power switching applications

Symbol	Test Conditions (T _J = 25°C, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
g_{fs}	V _{DS} = 10V, I _D = 60A, Note 1	57	95	S
C_{iss} C_{oss} C_{rss}	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz	20	nF	
		2450	pF	
		27	pF	
t_{d(on)} t_r t_{d(off)} t_f	Resistive Switching Times V _{GS} = 10V, V _{DS} = 0.5 • V _{DSS} , I _D = 85A R _G = 1Ω (External)	41	ns	
		29	ns	
		79	ns	
		16	ns	
Q_{g(on)} Q_{gs} Q_{gd}	V _{GS} = 10V, V _{DS} = 0.5 • V _{DSS} , I _D = 85A	258	nC	
		82	nC	
		78	nC	
R_{thJC}			0.14	°C/W
R_{thCS}		0.05		°C/W

Source-Drain Diode**Characteristic Values**
(T_J = 25°C, unless otherwise specified)

Symbol	Test Conditions	Min.	Typ.	Max.
I _s	V _{GS} = 0V		170	A
I _{SM}	Repetitive, pulse width limited by T _{JM}		500	A
V _{SD}	I _F = 85A, V _{GS} = 0V, Note 1		1.3	V
t_{rr} Q_{RM} I_{RM}	I _F = 85A, -di/dt = 150A/μs V _R = 100V	1.85	200	ns
		21		μC
				A

Note 1: Pulse test, t ≤ 300μs; duty cycle, d ≤ 2%.

SOT-227B Outline

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.240	1.255	31.50	31.88
B	.307	.323	7.80	8.20
C	.161	.169	4.09	4.29
D	.161	.169	4.09	4.29
E	.161	.169	4.09	4.29
F	.587	.595	14.91	15.11
G	1.186	1.193	30.12	30.30
H	1.496	1.505	38.00	38.23
J	.460	.481	11.68	12.22
K	.351	.378	8.92	9.60
L	.030	.033	0.76	0.84
M	.496	.506	12.60	12.85
N	.990	1.001	25.15	25.42
O	.078	.084	1.98	2.13
P	.195	.235	4.95	5.97
Q	1.045	1.059	26.54	26.90
R	.155	.174	3.94	4.42
S	.186	.191	4.72	4.85
T	.968	.987	24.59	25.07
U	-.002	.004	-0.05	0.1

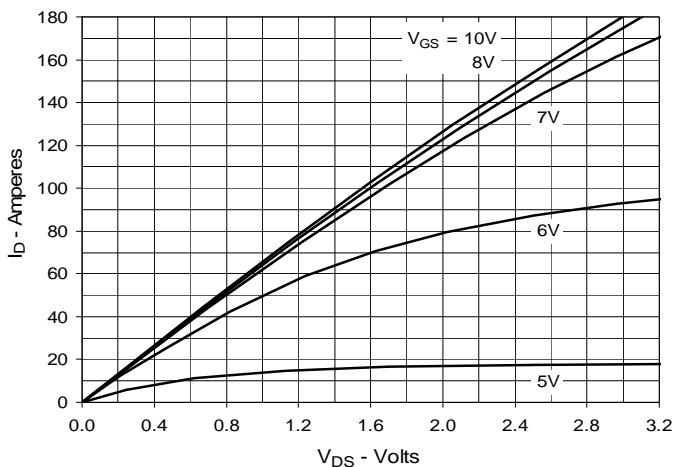
PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

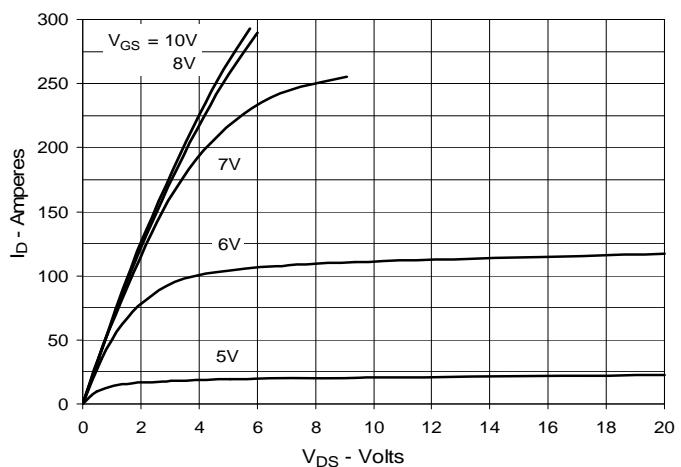
IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

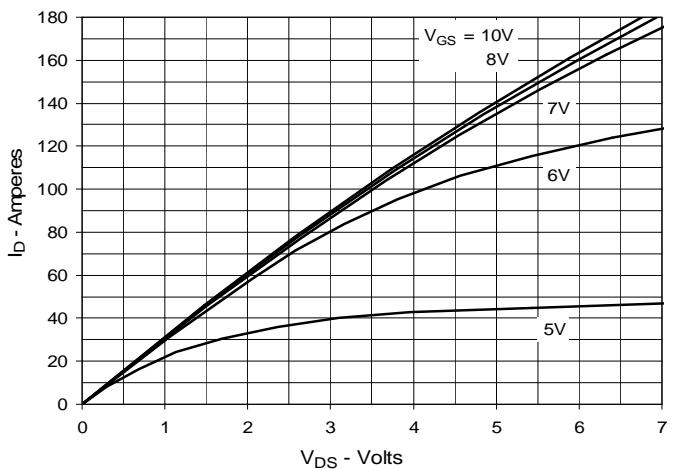
**Fig. 1. Output Characteristics
@ 25°C**



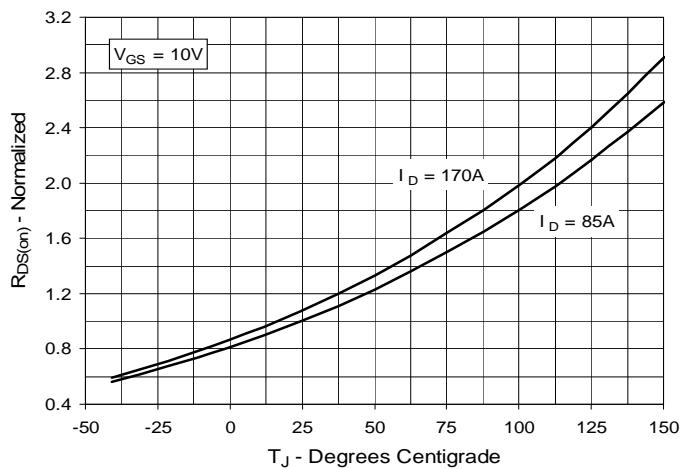
**Fig. 2. Extended Output Characteristics
@ 25°C**



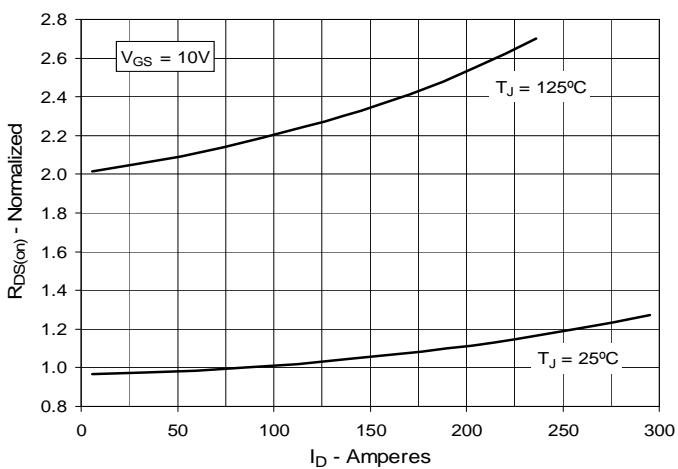
**Fig. 3. Output Characteristics
@ 125°C**



**Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 85A$ Value
vs. Junction Temperature**



**Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 85A$ Value
vs. Drain Current**



**Fig. 6. Maximum Drain Current vs.
Case Temperature**

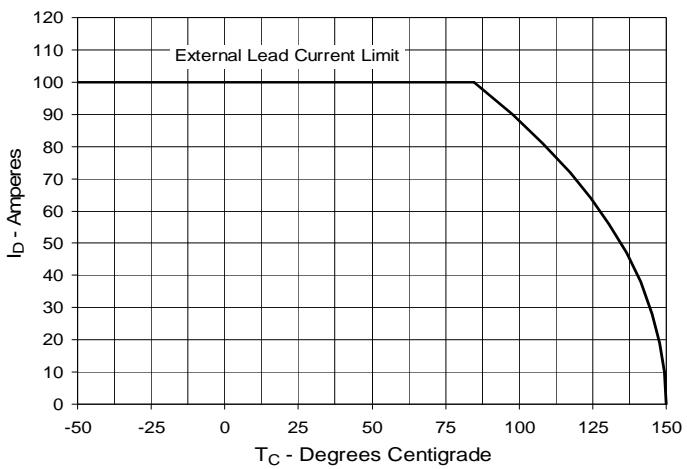
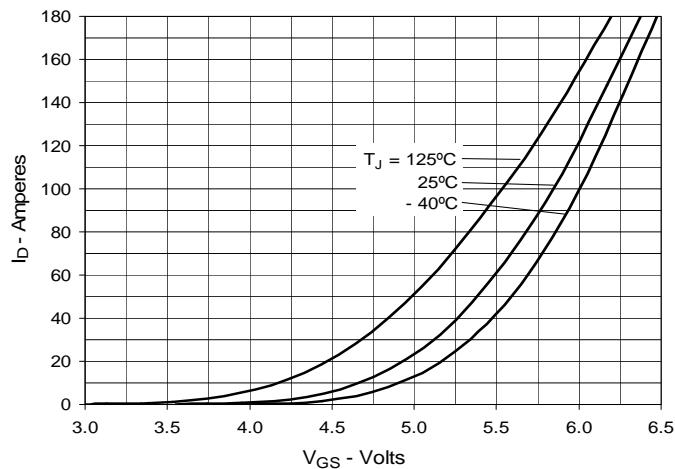
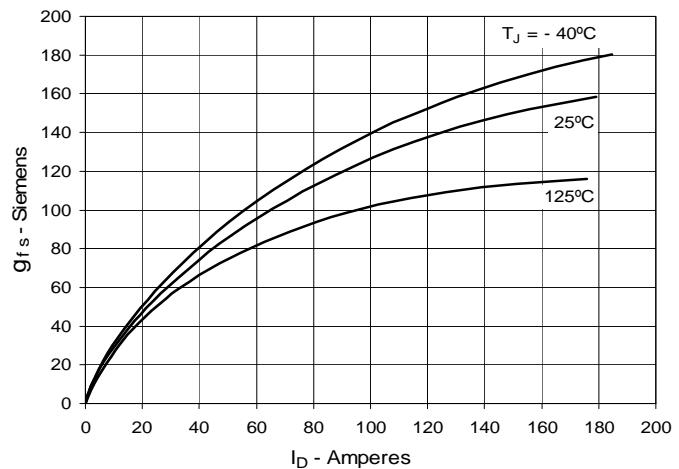
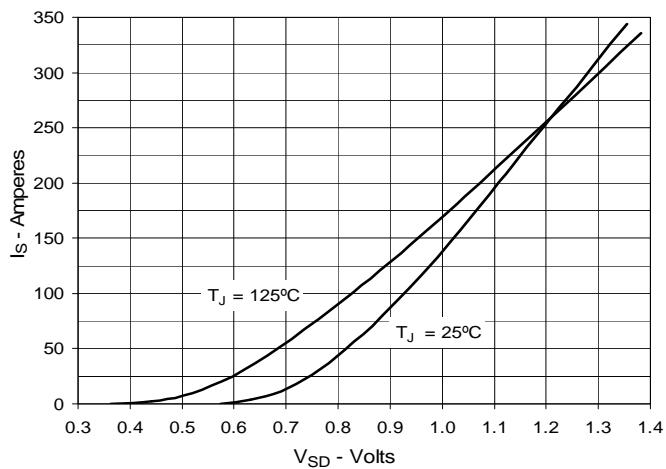
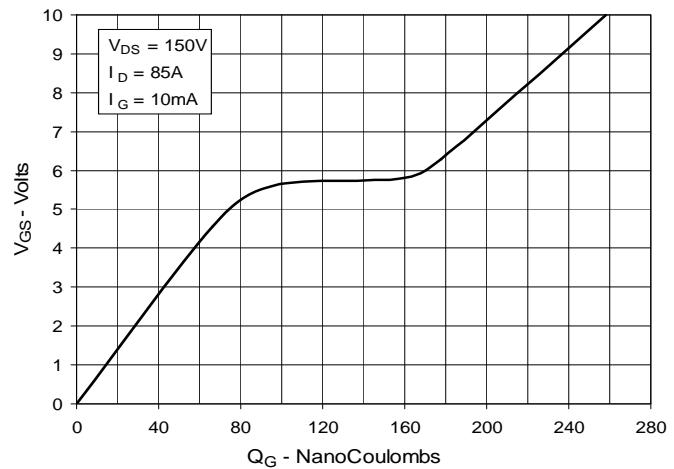
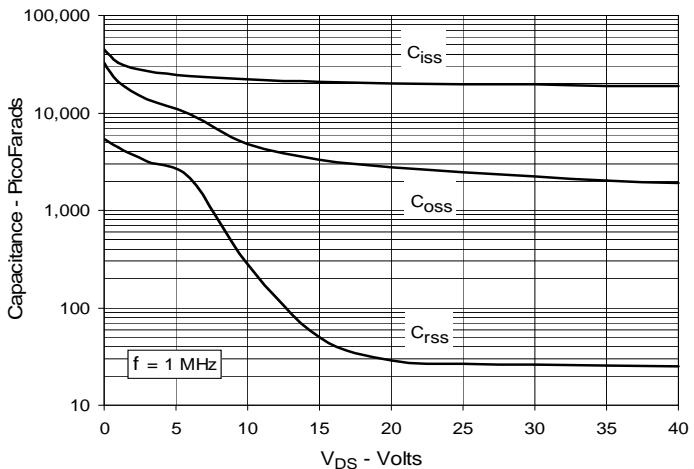
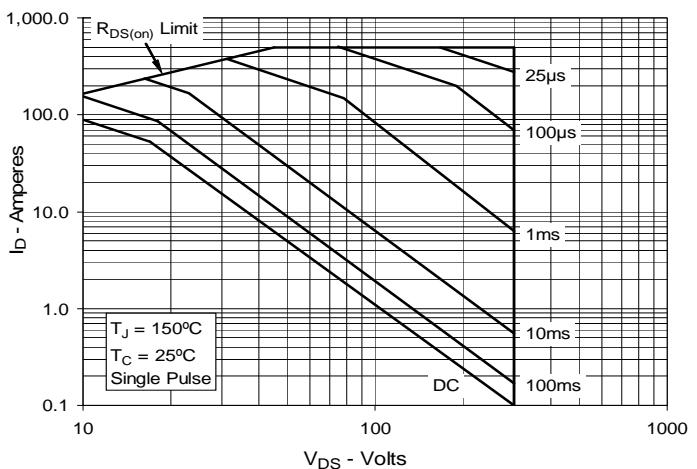


Fig. 7. Input Admittance**Fig. 8. Transconductance****Fig. 9. Forward Voltage Drop of Intrinsic Diode****Fig. 10. Gate Charge****Fig. 11. Capacitance****Fig. 12. Forward-Bias Safe Operating Area**

IXYS reserves the right to change limits, test conditions, and dimensions.

Fig. 12. Maximum Transient Thermal Impedance